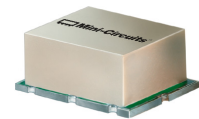


Surface Mount Attenuator/Switch

SYAS-1+

50Ω Bi-Phase 2 to 400 MHz



CASE STYLE: TTT166

Maximum Ratings

Operating Temperature	-40°C to 85°C
Storage Temperature	-55°C to 100°C
Control Current	30mA
Permanent damage may occur if any of these limits are exceeded.	

Pin Connections

INPUT	1
OUTPUT	2
CONTROL	3
GROUND	4,5,6

Features

- low conversion loss, 1.6 dB typ.
- excellent amplitude and phase unbalance

Applications

- electronic attenuator

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Attenuator/Switch Electrical Specifications

FREQUENCY (MHz)	CON	INSERTION LOSS (dB) ±20 mA				MAX. INPUT PWR (dBm) ±20 mA	IN-OUT ISOLATION (dB) 0 mA						BI-PHASE X (±20 mA) Typ.				
		Mid-Band m		Total Range			L		M		U		Δ AMP (dB)		Phase (deg.) deviation from 180°		
f _L -f _U		Typ.	Max.	Typ.	Max.	1 dB compr.	no damage	Typ.	Min.	Typ.	Min.	Typ.	Min.	m	Total Range	m	Total Range
2-400	DC-0.05	1.4	2.0	1.6	3.0	20*	25	65	45	45	33	35	25	0.1	0.1	1.0	2.0

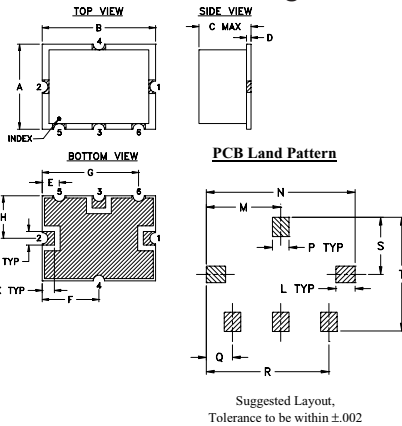
L = low range [f_L to 10 f_L] M = mid range [10 f_L to f_U/2] U = upper range [f_U/2 to f_U] m = [2 f_L to f_U/2]
* 15 dBm from 2-10 MHz.

Performance specifications apply for input power up to 10 dB below stated 1 dB compression.

Typical Performance Data

Freq. (MHz)	I. Loss (dB) at 20mA	±Control ΔAMP (dB)	20mA ΔPhase (deg.)	Isolation (dB)		Input R. Loss (dB)	Control Current (mA)	Attenuation (dB)			Phase Δ ref at 15mA Ctrl (deg.)			Input VSWR			
				(in-out)	(in-con)			2 MHz	200 MHz	400 MHz	2 MHz	200 MHz	400 MHz	2 MHz	200 MHz	400 MHz	
X	σ	X	X	X	X	X											
2.0	1.67	0.000	0.01	179.9	78	54	18.1	0.0000	72.7	39.0	30.6	27.2	-87.7	-95.3	7.7	7.2	4.4
7.0	1.16	0.001	0.00	180.0	68	43	15.4	0.0003	64.4	39.2	30.7	22.2	-86.0	-94.6	7.7	7.2	4.4
10.0	1.16	0.001	0.00	180.0	66	40	27.6	0.0005	56.5	39.0	30.8	28.6	-84.3	-93.7	7.6	7.2	4.4
21.9	1.16	0.001	0.00	180.0	58	33	31.0	0.0012	50.4	39.0	30.7	17.6	-80.5	-92.0	7.6	7.2	4.4
39.8	1.19	0.001	0.00	180.1	53	28	31.9	0.0019	47.8	39.0	30.7	14.1	-77.4	-90.3	7.5	7.2	4.4
59.7	1.23	0.001	0.00	180.1	50	25	32.1	0.0054	42.5	37.9	30.6	8.2	-56.2	-79.9	7.4	7.0	4.3
61.7	1.23	0.001	0.00	180.1	50	25	32.1	0.0100	38.4	35.8	30.1	7.6	-37.3	-67.6	7.2	6.9	4.3
81.6	1.24	0.001	0.00	180.2	47	22	32.2	0.0157	35.1	33.1	29.0	8.8	-25.3	-55.1	7.1	6.7	4.2
99.5	1.27	0.001	0.00	180.2	46	21	32.3	0.0284	30.6	28.7	26.3	8.8	-12.8	-37.6	6.7	6.3	4.0
121.4	1.31	0.001	0.01	180.3	44	19	32.4	0.0433	27.3	25.3	23.7	9.2	-7.2	-26.9	6.3	5.9	3.8
141.3	1.32	0.001	0.01	180.4	42	18	32.4	0.0722	23.2	21.2	20.0	9.3	-3.1	-17.7	5.6	5.3	3.5
181.1	1.37	0.001	0.01	180.6	39	16	32.2	0.1012	20.7	18.6	17.6	9.0	-1.4	-13.2	5.2	4.9	3.3
200.0	1.40	0.001	0.01	180.6	39	15	32.0	0.1898	16.1	14.1	13.3	8.2	0.4	-8.0	4.1	3.9	2.8
220.9	1.39	0.001	0.01	180.8	38	15	31.6	0.3008	13.1	11.2	10.6	7.4	0.9	-5.5	3.4	3.2	2.4
240.8	1.39	0.001	0.01	180.9	36	14	30.3	0.4259	10.9	9.2	8.8	6.7	1.1	-4.2	2.9	2.7	2.1
280.6	1.52	0.001	0.05	181.1	35	13	26.6	0.7017	8.3	6.9	6.6	5.4	1.1	-2.8	2.2	2.1	1.7
300.5	1.52	0.001	0.04	181.1	35	14	24.8	0.9968	6.8	5.6	5.4	4.4	0.9	-2.1	1.9	1.8	1.5
340.3	1.56	0.001	0.03	181.4	33	13	21.4	1.7486	4.8	3.9	4.0	3.0	0.7	-1.3	1.5	1.5	1.3
360.2	1.64	0.002	0.06	181.6	32	13	19.8	5.6920	2.5	2.1	2.3	0.9	0.2	-0.3	1.2	1.1	1.2
400.0	1.78	0.003	0.09	181.7	31	14	17.1	15.1258	1.8	1.5	1.8	0.0	0.0	0.1	1.3	1.1	1.3

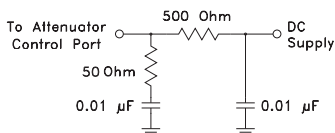
Outline Drawing



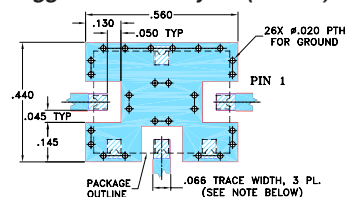
Outline Dimensions (inch)

A	B	C	D	E	F	G	H	J	K
.38	.50	.23	.020	.075	.250	.425	.187	.050	.050
9.65	12.70	5.84	0.51	1.91	6.35	10.80	4.75	1.27	1.27
L	M	N	P	Q	R	S	T	wt.	
.070	.270	.540	.060	.095	.445	.208	.415	grams	
1.78	6.86	13.72	1.52	2.41	11.30	5.28	10.54	0.8	

suggested control port biasing configuration



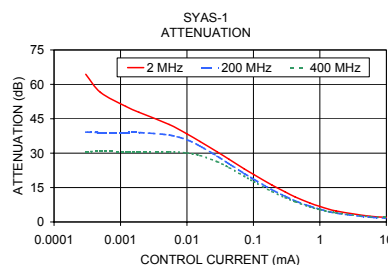
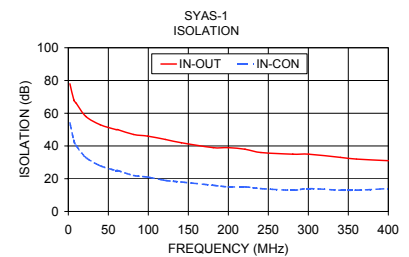
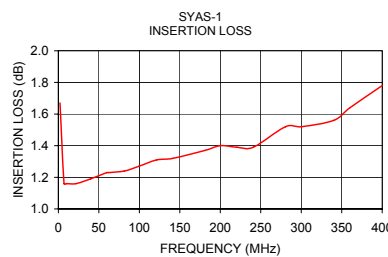
Demo Board MCL P/N: TB-12 Suggested PCB Layout (PL-079)



- NOTE:
1. TRACE WIDTH IS SHOWN FOR ROGERS R04350B WITH DIELECTRIC THICKNESS .030" ± .002"; COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
 2. THE USE OF SOLDER MASK OVER THE GROUND AREA UNDER THE UNIT AS SHOWN IS RECOMMENDED TO PREVENT POTENTIAL SHORTING. IF USER CHOOSES TO EXPOSE METAL UNDER THE CENTRE UNIT GROUND PAD FOR IMPROVED GROUNDING, IT IS RECOMMENDED A SOLDER MASK DAM BE APPLIED AROUND EACH GROUND PAD TO ENSURE TILLET AND CONNECTION AT GROUND PADS.
 3. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
- DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER), SEE NOTE 2.

Notes

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuits' applicable established test performance criteria and measurement instructions.
- C. The parts covered by this specification document are subject to Mini-Circuits' standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/MCLStore/terms.jsp



electrical schematic

